

STP36N60M6, STW36N60M6

N-channel 600 V, 85 mΩ typ., 30 A MDmesh™ M6 Power MOSFETs in TO-220 and TO-247 packages

Datasheet - production data

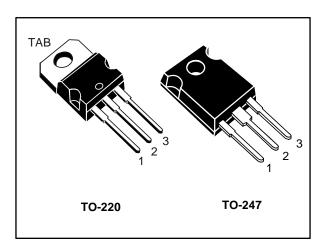
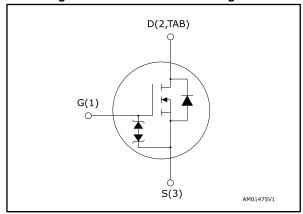


Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	ΙD
STP36N60M6	600 V	000	20.4
STW36N60M6	000 V	99 mΩ	30 A

- Reduced switching losses
- Lower R_{DS(on)} x area vs previous generation
- Low gate input resistance
- 100% avalanche tested
- Zener-protected

Applications

Switching applications

Description

The new MDmeshTM M6 technology incorporates the most recent advancements to the well-known and consolidated MDmesh family of SJ MOSFETs. STMicroelectronics builds on the previous generation of MDmesh devices through its new M6 technology, which combines excellent $R_{DS(on)}$ * area improvement with one of the most effective switching behaviors available, as well as a user-friendly experience for maximum endapplication efficiency.

Table 1: Device summary

Order code	Marking	Package	Packaging
STP36N60M6	OCNICOMO	TO-220	Tuba
STW36N60M6	36N60M6	TO-247	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
Vgs	Gate-source voltage	±25	V
I_D	Drain current (continuous) at T _C = 25 °C	30	Α
ΙD	Drain current (continuous) at T _C = 100 °C	19	Α
I _D ⁽¹⁾	Drain current (pulsed)	102	Α
P _{TOT}	Total dissipation at T _C = 25 °C	208	W
dv/dt ⁽²⁾	Peak diode recovery voltage slope	15	V/ns
dv/dt ⁽³⁾	MOSFET dv/dt ruggedness	50	V/ns
T _{stg}	Storage temperature range	-55 to 150	°C
Tj	Operating junction temperature range	-55 10 150	C

Notes:

Table 3: Thermal data

Symbol	Parameter		Value		Unit
Syllibol			TO-247	Ollit	
R _{thj-case}	Thermal resistance junction-case	0.6		°C/W	
R _{thj-amb}	Thermal resistance junction-ambient	62.5	50	°C/W	

Table 4: Avalanche characteristics

Symbol	Parameter	Value	Unit
I _{AR}	Avalanche current, repetitive or not repetitive (pulse width limited by T _{jmax})	5	А
E _{AS}	Single pulse avalanche energy (starting $T_j = 25$ °C, $I_D = I_{AR}$, $V_{DD} = 50$ V)	750	mJ

 $[\]ensuremath{^{(1)}}\mbox{Pulse}$ width limited by safe operating area.

 $^{^{(2)}}I_{SD} \leq 30$ A, di/dt ≤ 400 A/µs, $V_{DS(peak)} < V_{(BR)DSS}, \, V_{DD} = 400$ V.

 $^{^{(3)}}V_{DS} \le 480 \text{ V}$

2 Electrical characteristics

T_C = 25 °C unless otherwise specified

Table 5: On/off states

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	600			V
	Zoro goto voltago drain	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V}$			1	μΑ
I _{DSS}	Zero gate voltage drain current	$V_{GS} = 0 \text{ V}, V_{DS} = 600 \text{ V},$ $T_{C} = 125 \text{ °C}^{(1)}$			100	μΑ
I _{GSS}	Gate-body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			±5	μΑ
V _{GS(th)}	Gate threshold voltage	$V_{DS} = V_{GS}, I_{D} = 250 \ \mu A$	3.25	4	4.75	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = 10 V, I _D = 15 A		85	99	mΩ

Notes:

Table 6: Dynamic

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
Ciss	Input capacitance		-	1960	ı	pF
Coss	Output capacitance	V _{DS} = 100 V, f = 1 MHz,	-	93	-	pF
C _{rss}	Reverse transfer capacitance	Ves = 0 V	-	6	-	pF
Coss eq. (1)	Equivalent output capacitance	V _{DS} = 0 to 480 V, V _{GS} = 0 V	1	332	ı	pF
Rg	Intrinsic gate resistance	f = 1 MHz, I _D = 0 A	-	1.6	ı	Ω
Q_g	Total gate charge	$V_{DD} = 480 \text{ V}, I_D = 30 \text{ A},$	-	44.3	-	nC
Qgs	Gate-source charge	V _{GS} = 0 to 10 V (see Figure 17: "Test circuit for	-	10.1	ı	nC
Q_{gd}	Gate-drain charge	gate charge behavior")	-	25	-	nC

Notes:

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⁽¹⁾Defined by design, not subject to production test.

 $^{^{(1)}}C_{oss\ eq.}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS}

Table 7: Switching times

Tuble 7. Owicoming times							
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit	
t _{d(on)}	Turn-on delay time	$V_{DD} = 300 \text{ V}, I_D = 15 \text{ A},$	ı	15.2	-	ns	
tr	Rise time	$R_G = 4.7 \Omega$, $V_{GS} = 10 V$ (see Figure 18: "Test circuit for	ı	5.3	-	ns	
t _{d(off)}	Turn-off-delay time	inductive load switching and	-	50.2	-	ns	
t _f	Fall time	diode recovery times" and Figure 21: "Switching time waveform")	-	7.3	-	ns	

Table 8: Source drain diode

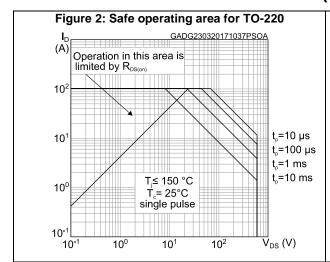
Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit
I _{SD}	Source-drain current		ı		30	Α
I _{SDM} ,(1)	Source-drain current (pulsed)		-		102	Α
V _{SD} (2)	Forward on voltage	V _{GS} = 0 V, I _{SD} = 30 A	ı		1.6	V
t _{rr}	Reverse recovery time	$I_{SD} = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	ı	340		ns
Q_{rr}	Reverse recovery charge	V _{DD} = 60 V (see Figure 18: "Test circuit for	-	5.3		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	1	31		А
t _{rr}	Reverse recovery time	$I_{SD} = 30 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	430		ns
Qrr	Reverse recovery charge	$V_{DD} = 60 \text{ V}, T_j = 150 \text{ °C}$ (see Figure 18: "Test circuit for	-	7.7		μC
I _{RRM}	Reverse recovery current	inductive load switching and diode recovery times")	-	36		Α

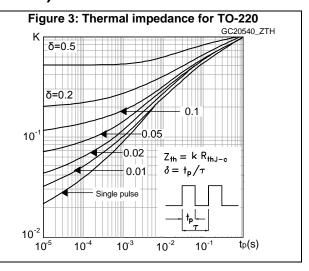
Notes

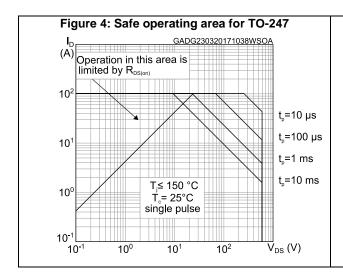
⁽¹⁾Pulse width is limited by safe operating area.

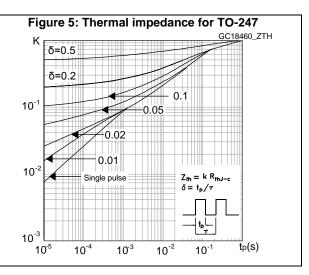
 $^{^{(2)}\}text{Pulsed:}$ pulse duration = 300 $\mu\text{s},$ duty cycle 1.5%

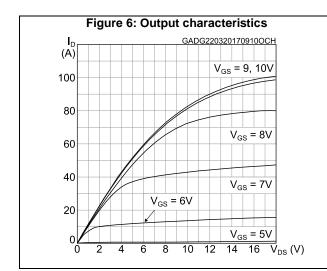
2.1 Electrical characteristics (curves)

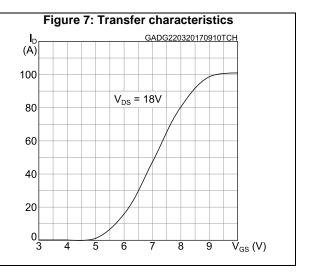






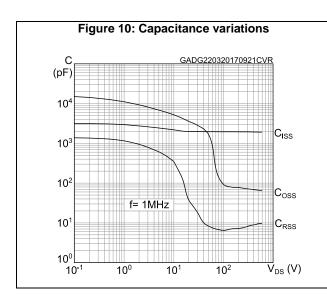


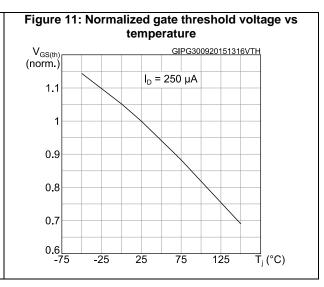


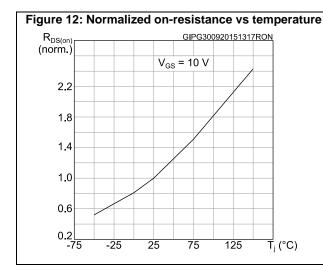


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Figure 8: Gate charge vs gate-source voltage GADG030220171159QVG V_{DS} $V_{DD} = 480 \text{ V}$ $I_{\rm D} = 30 \, {\rm A}$ V_{DS} $\overline{\overline{Q}}_{g}$ (nC)







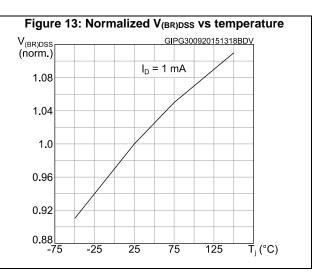


Figure 14: Output capacitance stored energy

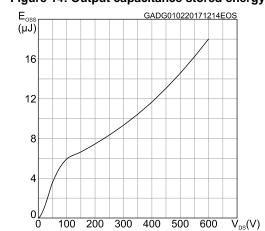
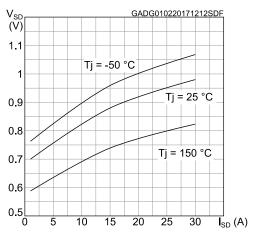


Figure 15: Source-drain diode forward characteristics

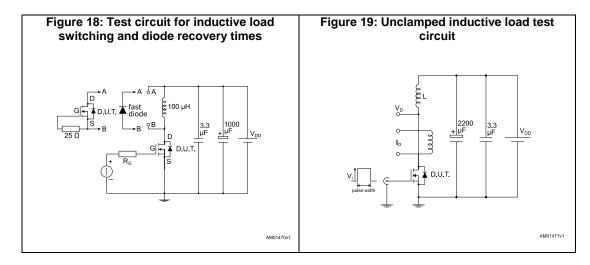


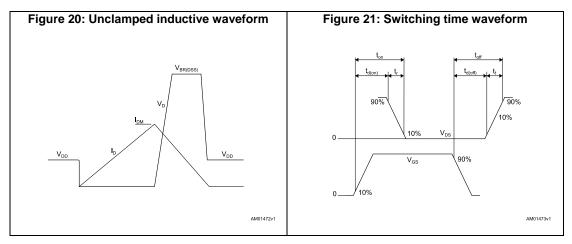
3 Test circuits

Figure 16: Test circuit for resistive load switching times

Figure 17: Test circuit for gate charge behavior

Figure 17: Test circuit for gate charge behavior





4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

4.1 TO-220 type A package information

Figure 22: TO-220 type A package outline

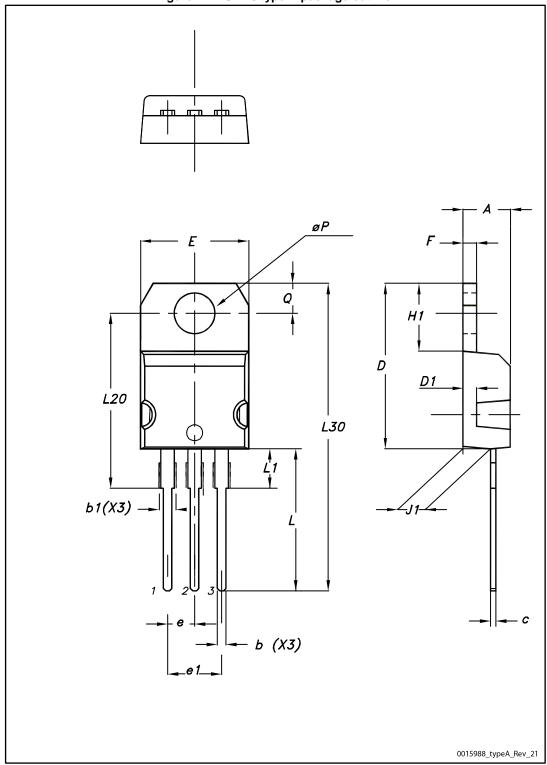


Table 9: TO-220 type A mechanical data

		mm	
Dim.	Min.	Тур.	Max.
А	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
С	0.48		0.70
D	15.25		15.75
D1		1.27	
Е	10.00		10.40
е	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øΡ	3.75		3.85
Q	2.65		2.95

4.2 TO-247 package information

Figure 23: TO-247 package outline

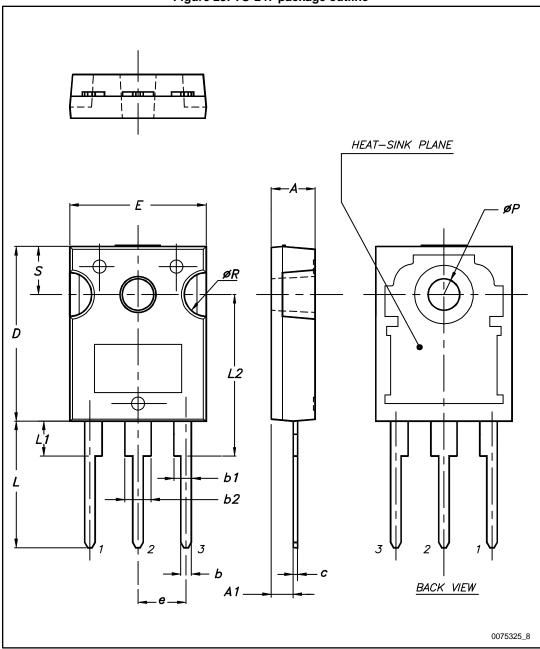


Table 10: TO-247 package mechanical data

Dim		mm	
Dim.	Min.	Тур.	Max.
А	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
С	0.40		0.80
D	19.85		20.15
Е	15.45		15.75
е	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
06-Oct-2015	1	First release
14-Oct-2015	2	Updated: V _{DD} value in <i>Table 8: "Source drain diode"</i> Minor text changes
27-Mar-2017	3	Updated Table 2: "Absolute maximum ratings". Updated Section 2: "Electrical characteristics". Updated Section 4: "Package information". Minor text changes

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